

技术及应用

CMOS器件辐照后热退火过程中激发能分布的确定

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摘要 对CNMOS晶体管辐照后的等温、等时退火特性进行讨论, 给出辐照敏感参数在等温、等时退火过程中随退火时间、退火温度的变化关系。根据退火模型计算了CMOS器件辐照后25、100 °C等温和25~250 °C等时退火过程中激发能的分布。结果表明: 25、100 °C等温退火激发能范围分别在0.65~0.76 eV和0.75~0.95 eV之间; 25~250 °C等时退火的激发能范围在0.5~1.1 eV之间, 峰值位于0.81 eV。

关键词

[等时退火](#) [等温退火](#) [激发能](#)

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Determination of Activation Energy Distribution During Thermal Annealing in Post-Irradiation CMOS Devices

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Abstract

The annealing characteristics of isothermal and isochronal for post-irradiation CMOS transistor are discussed. The relations about radiation sensitive parameters with isothermal annealing time and isochronal annealing temperature are given. The activation energy distribution during 25, 100 °C isothermal annealing and 25-250 °C isochronal annealing for post-irradiation CMOS devices are calculated by annealing model. According to the result, the range of activation energy for isothermal annealing at 25, 100 °C is from 0.65 eV to 0.76 eV and from 0.75 eV to 0.95 eV respectively. The range of activation energy for isochronal annealing is from 0.5 eV to 1.1 eV, and the peak is located at 0.81 eV.

Key words [isothermal annealing](#) [isochronal annealing](#) [activation energy](#)

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